

## Ratings and Characteristics Curves

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

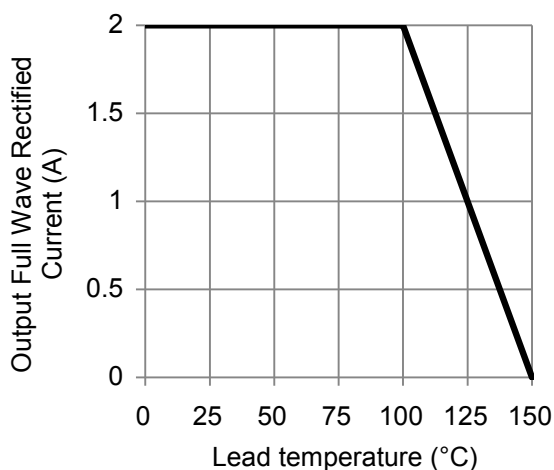


Figure 1. Forward Current Derating Curve

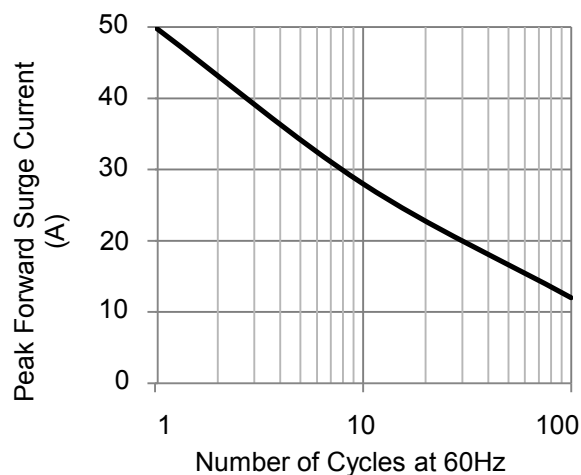


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

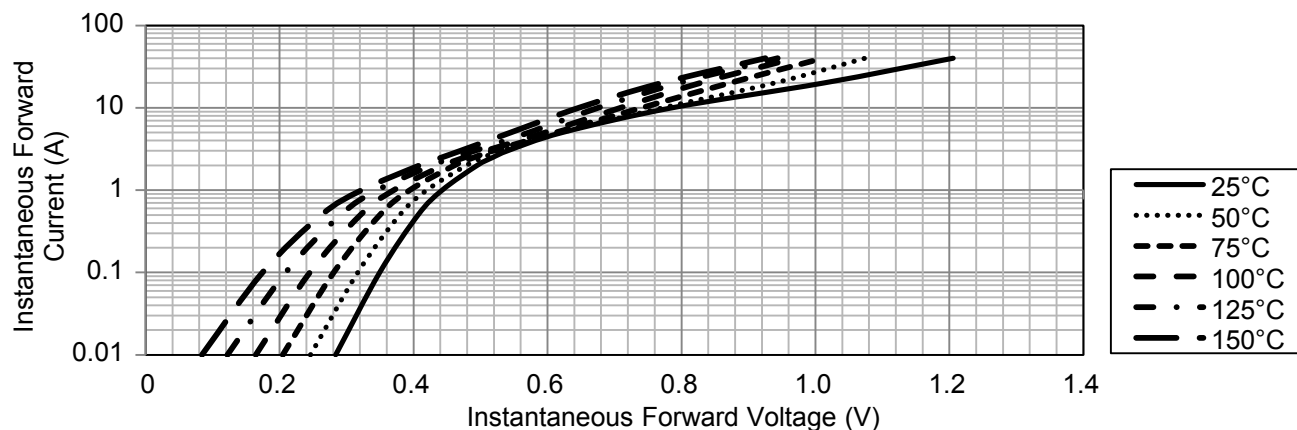


Figure 3. Typical Instantaneous Forward Characteristics  
(SK22A thru SK24A)

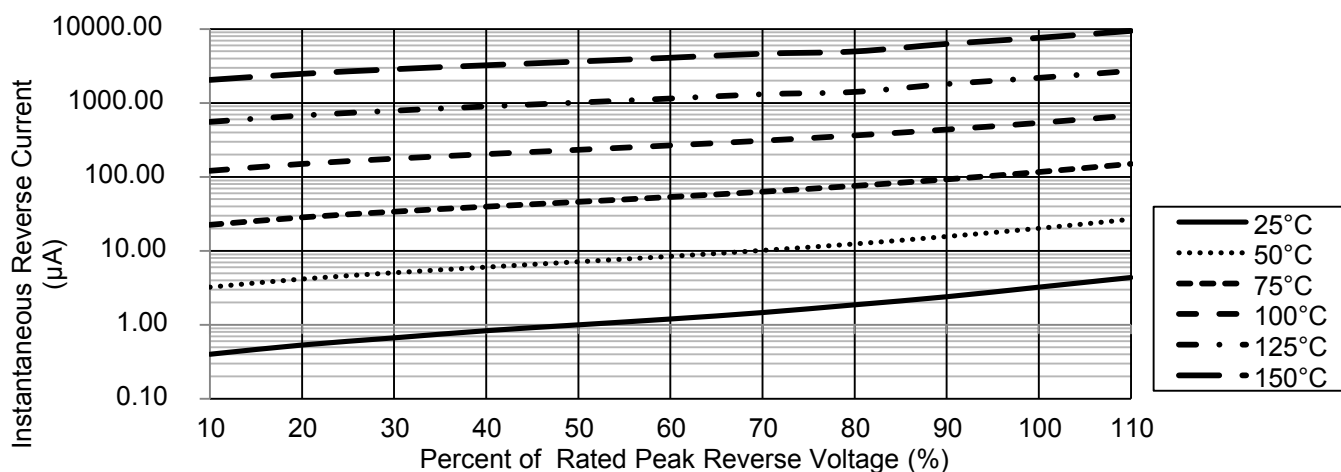


Figure 4. Typical Reverse Characteristics  
(SK22A thru SK24A)

# SK22A thru SK26A

Surface Mount Schottky Rectifier  
 Reverse Voltage 20-60V Forward Current 2A

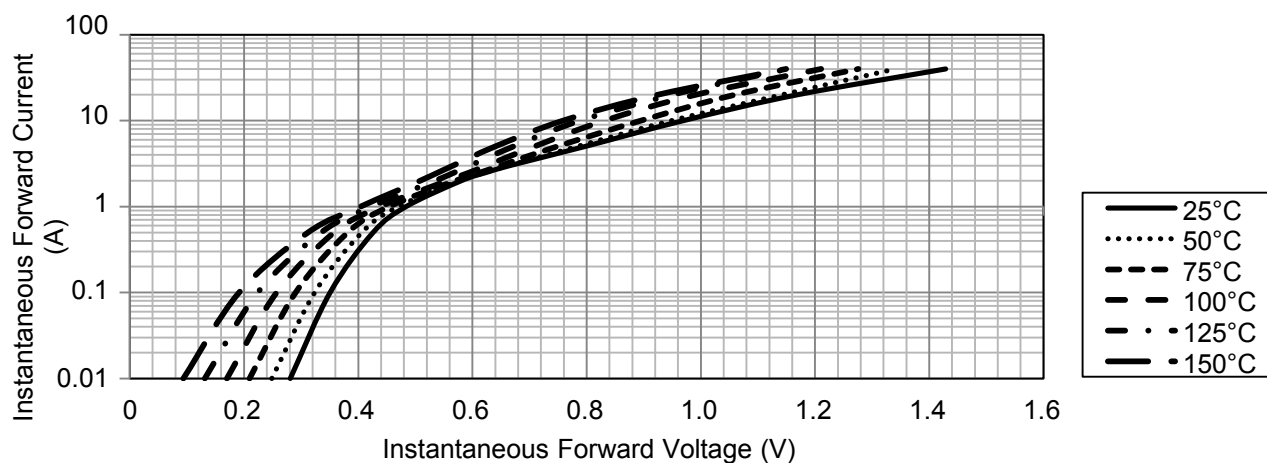


Figure 5. Typical Instantaneous Forward Characteristics  
 (SK25A thru SK26A)

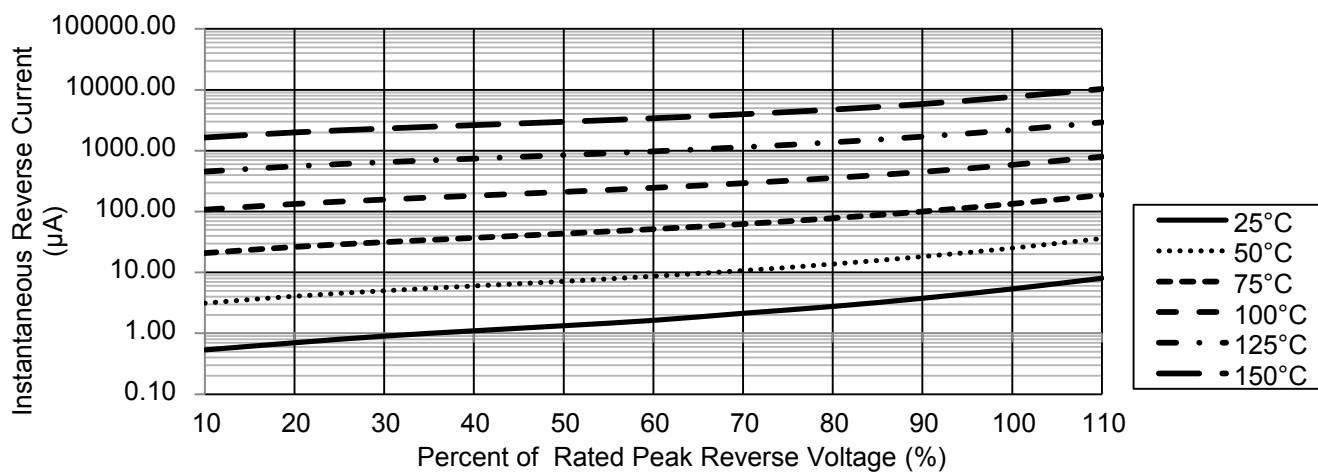


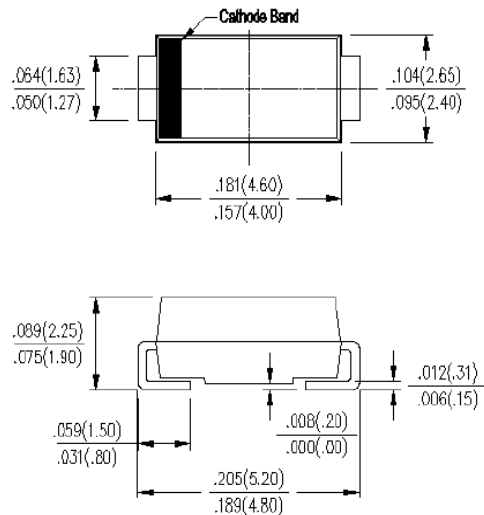
Figure 6. Typical Reverse Characteristics  
 (SK25A thru SK26A)

# SK22A thru SK26A

Surface Mount Schottky Rectifier  
Reverse Voltage 20-60V Forward Current 2A

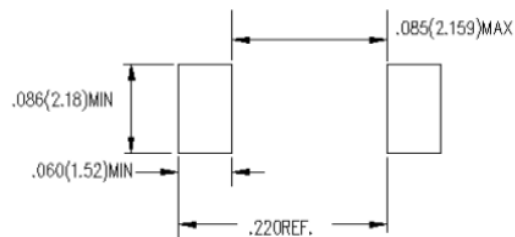
## Package Outline Dimensions

in inches (millimeters)



## DO-214AC (SMA)

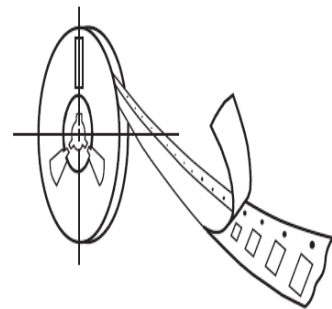
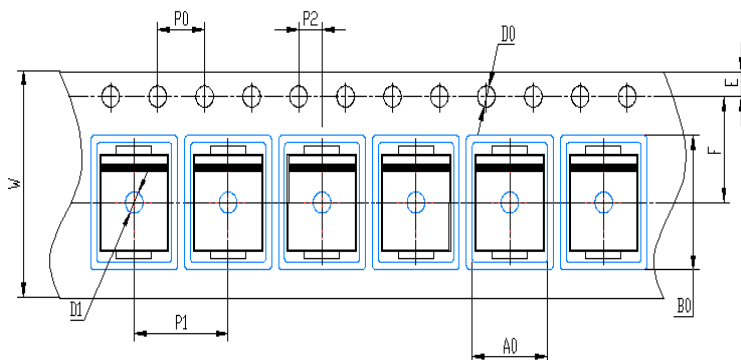
### MOUNTING PAD LAYOUT



## Packing Information

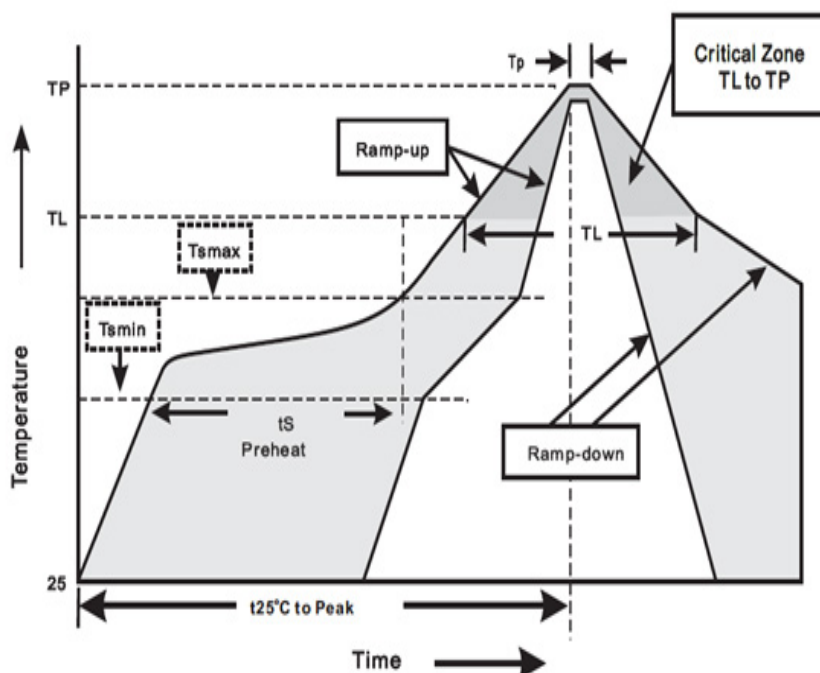
7500 pcs/Reel, 18 Reels/Box, 12mm Tape, 13" Reel

### Tape & Reel Specification



| Symbol | SMA(mm)      |
|--------|--------------|
| W      | 12±0.2       |
| E      | 1.75±0.1     |
| F      | 5.5±0.05     |
| D0     | 1.5±0.1      |
| D1     | 1.50 +0.1/-0 |
| P0     | 4.0±0.1      |
| P1     | 4.0±0.1      |
| P2     | 2.0±0.05     |
| A0     | 2.65±0.1     |
| B0     | 5.25±0.1     |

## Soldering Parameters



| Reflow Soldering                                  |                               | Sn-Pb Eutectic Assembly | Pb-Free Assembly |
|---------------------------------------------------|-------------------------------|-------------------------|------------------|
| Pre Heat                                          | - Temperature Min (Ts min)    | 100°C                   | 150°C            |
|                                                   | - Temperature Max (Ts max)    | 150°C                   | 200°C            |
|                                                   | - Time (min to max) (ts)      | 60 – 120 secs           | 60 – 180 secs    |
| Average ramp up rate (Liquidus) Temp (TL) to peak |                               | 3°C/second max          | 3°C/second max   |
| TS(max) to TL - Ramp-up Rate                      |                               | 3°C/second max          | 3°C/second max   |
| Reflow                                            | - Temperature (TL) (Liquidus) | 183°C                   | 217°C            |
|                                                   | - Time (min to max) (ts)      | 60 – 150 seconds        | 60 – 150 seconds |
| Peak Temperature (TP)                             |                               | 240+0/-5 °C             | 240+0/-5°C       |
| Time within 5°C of actual peak Temperature (tp)   |                               | 10 – 30 seconds         | 20 – 40 seconds  |
| Ramp-down Rate                                    |                               | 6°C/second max          | 6°C/second max   |
| Time 25°C to peak Temperature (TP)                |                               | 6 minutes max           | 8 minutes max    |
| Do not exceed                                     |                               | 260°C                   | 260°C            |

| Wave Soldering   |            |
|------------------|------------|
| Peak Temperature | 260+0/-5°C |
| Dipping Time     | 10 seconds |
| Soldering        | 1 time     |